



# Product Change Notification

**Change Notification #:** 117126 - 01

**Change Title:** Intel® Server System R1304WFTYS ,  
PCN 117126-01, Product Design, Label,  
Update BIOS/BMC/ME/FRUSDR, Firmware,  
1100W Power Supply Add URL to BIS mark,  
3.5" Tool-Less Carrier Design Improvement  
for 2.5" Drive Support  
**Reason for Revision: Correct Post-Change TA**

**Date of Publication:** September 09, 2019

## Key Characteristics of the Change:

Product Design, Label

## Forecasted Key Milestones:

|  |                   |
|--|-------------------|
| <b>Date Customer Must be Ready to Receive Post-Conversion Material:*</b> | September 5, 2019 |
|--|-------------------|

\* Intel appreciates the customer's desire to receive the latest revision of products. However, Intel manages inventory on a first in first out (FIFO) basis at the MM# level. Subsequently, customer requests for a specific revision of material (below the MM#) will not be supported by Intel.

## Description of Change to the Customer:

### Reason for Revision: Correct Post-Change TA

1. Update to the system firmware
  - a) Update BIOS revision to R00.01.3015
  - b) Update the Manageability Engine (ME) firmware revision to 04.00.04.340
  - c) Update the Baseboard Management Controller (BMC) firmware revision to 1.74ee39402a
  - d) Update the FRUSDR revision to 1.74

- Update the label of the 1100W power supply included in the Intel® Server System R1304WFTYS. The new label includes a URL of the BIS mark and remove “S&E” inside the CCC logo.

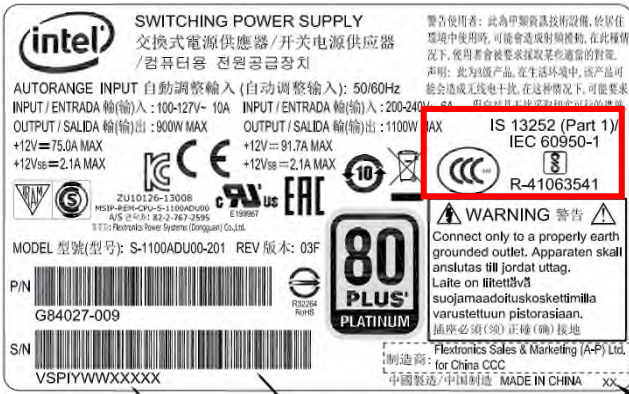


Image 1. Power supply label before change

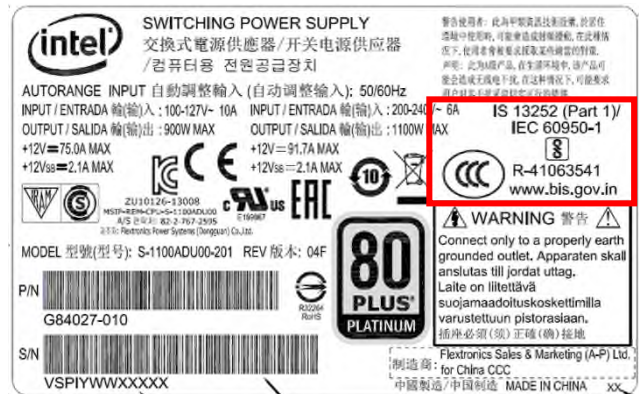
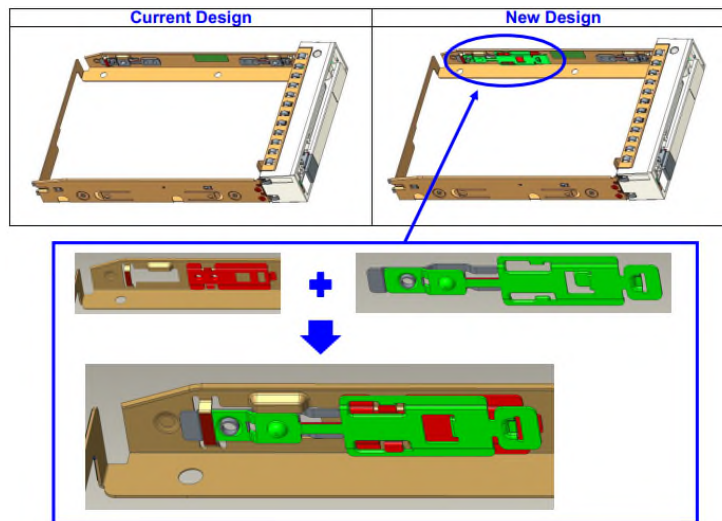


Image 2. Power supply label after

- Improvement for the 3.5” tool-less drive carrier when used for 2.5” drive support, from a non-removable to a new removable rear spring (see image in green) and new spring holder (see image in red) attached to the tool-less drive carrier.

Removing the new rear spring of 3.5” tool-less carrier when installing 2.5” SSD drive, installing the rear spring to support 3.5” HDD.



## Customer Impact of Change and Recommended Action:

Intel does not expect any other impact to customers from these changes, but encourages customers to understand the change and determine the impact on their applications. For that reason Intel recommends that the customer perform a standard level of evaluation. Customers can download and evaluate the latest BIOS/ME/Integrated BMC and FRUSDR release notes for more information at <http://www.intel.com/support>.

## Products Affected / Intel Ordering Codes:

| Product Code | MM#    | Pre- Change TA | Pre Change-PBA           | Post-Change TA             | Post- Change PBA         |
|--------------|--------|----------------|--------------------------|----------------------------|--------------------------|
| R1304WFTYS   | 975884 | H97411-013     | H48104-853<br>H48104-863 | <a href="#">H97411-014</a> | H48104-854<br>H48104-864 |

## PCN Revision History:

| Date of Revision:                 | Revision Number:   | Reason:                                |
|-----------------------------------|--------------------|--|
| August 21, 2019                   | 00                 | Originally Published PCN               |
| <a href="#">September 9, 2019</a> | <a href="#">01</a> | <a href="#">Correct Post-Change TA</a> |



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**Should you have any issues with the timeline or content of this change, please contact the Intel Representative(s) for your geographic location listed below. No response from customers will be deemed as acceptance of the change and the change will be implemented pursuant to the key milestones set forth in this attached PCN.**

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